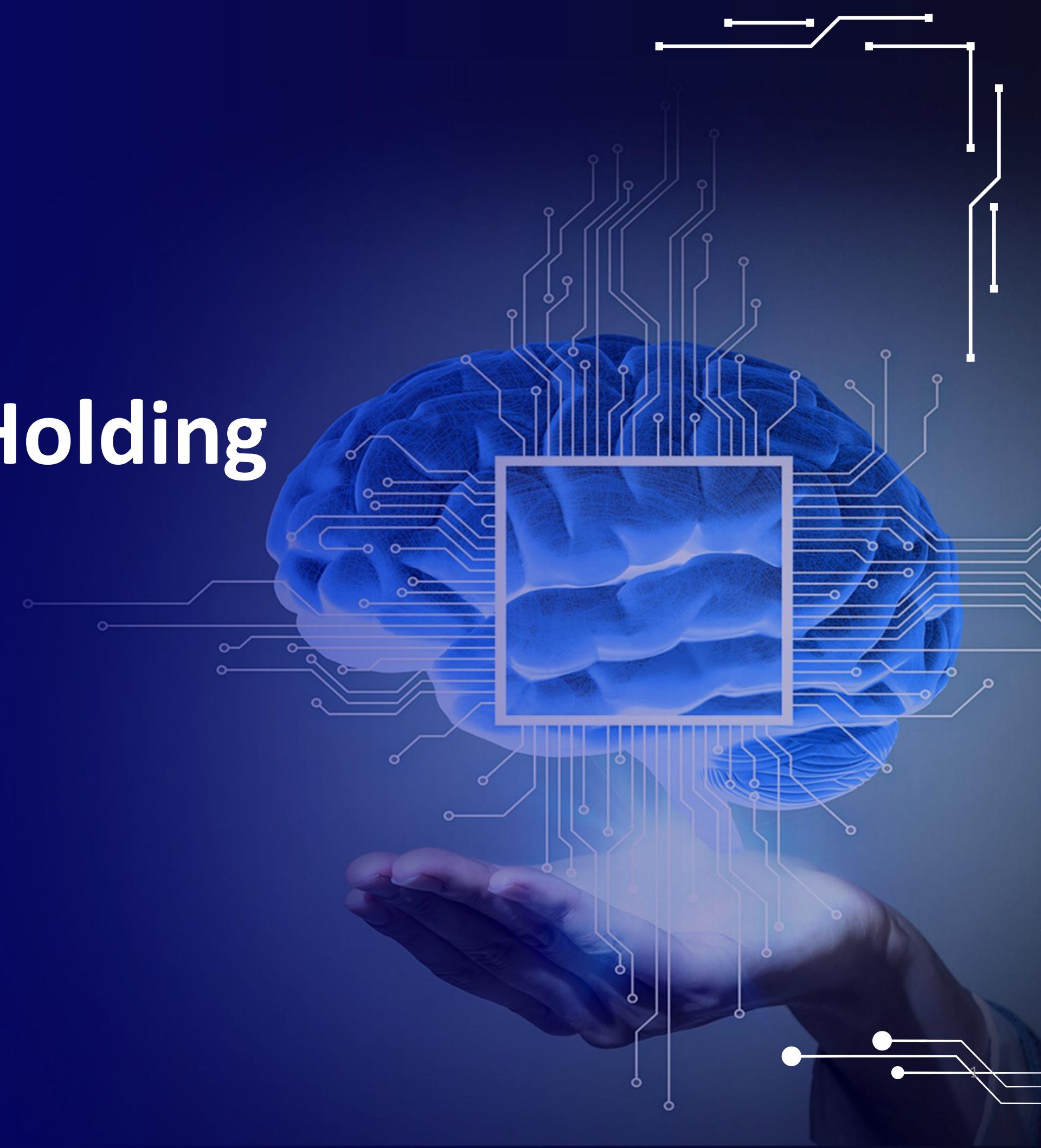


Zhen Ding Technology Holding (4958 TT)

Investor Presentation

December 2025



Safe Harbor Notice

- Zhen Ding Technology Holding's statements of its current expectations are forward looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.
- Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

Zhen Ding (ZDT) at a Glance



Global No. 1 PCB Manufacturer

2006 Founded
(Former Foxconn
Advanced Tech, 1978)

Taoyuan, Taiwan
Headquarter



32 Facilities
Located in Mainland
China, Taiwan,
Thailand and India

48,141
Employees as of End-2024

NT\$171.7bn

Revenue in 2024
(13.4% YoY)

+9%

2014-2024
Revenue CAGR



Key Growth Drivers

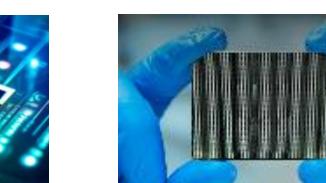
AI Server/Optical



AI Glasses



IC Substrate



Foldable Phone



NT\$149.1bn

Market Cap
(as of Nov. 21, 2025)

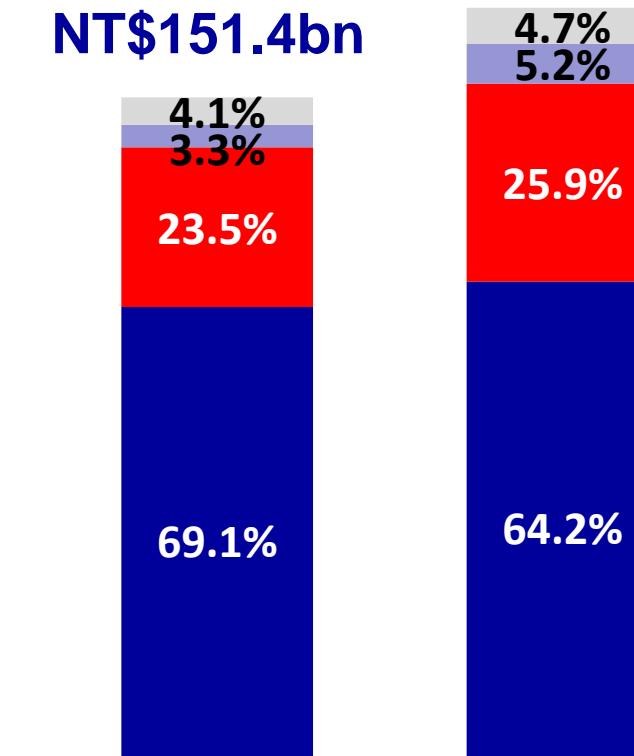
13.3%

10-yr Average ROE
(2015-2024)

Revenue Breakdown – By Applications

+13.4% YoY

NT\$171.7bn
NT\$151.4bn



Server / Automotive /
Optical and others

IC Substrate

Computer and Consumer
Electronics

Mobile Communications

2023

2024



Recent Business Update

Business Review and Outlook

- 1 Operating performance remained solid in 3Q25 and 1-3Q25:** 3Q25 revenue declined 6.4% YoY, mainly due to foreign exchange effects. In U.S. dollar terms, revenue increased 0.6% YoY. Gross margin for the quarter was 22.0%, down 0.5 percentage points from the same period last year, primarily reflecting continued investments in AI-related capacity, which led to a 0.6-percentage-point increase in depreciation-to-revenue ratio versus a year ago. For 1-3Q25, cumulative revenue rose 8.8% YoY to a record high for the same period. All four major application segments recorded YoY growth, with IC substrates posting the strongest increase of 30%. Gross margin and operating margin for 1-3Q25 both improved from a year earlier, up 0.3 and 1.2 percentage points, respectively.
- 2 4Q25 is expected to follow normal seasonality and reach this year's peak, with full-year 2025 revenue set to hit a new high:** 4Q25 remains a peak season for customers' new product shipments, with stable shipment momentum and high capacity utilization. For the IC substrate segment, BT substrate demand has shown a clear increase in 2H25, with average capacity utilization reaching 90-95%. Meanwhile, revenue contribution from large body size ABF substrates continues to rise, accompanied by a significant rise in sample builds.
- 3 Optimistic outlook for 2026, with all four major applications set to accelerate growth:** We are actively expanding our presence in AI server applications, offering Intelligent HDI (iHDI) and HLC products with a focus on next-generation customer platforms. AI server revenue is expected to gradually scale up in 2026 and double in 2027. For IC substrates, we plan to expand capacity at Qinhuangdao site starting in 1H26 to meet customer demand. Meanwhile, as sample builds for large body size AI compute-related ABF substrates increase significantly, revenue contribution is expected to increase materially quarter by quarter throughout 2026. For edge AI devices, growth momentum will be driven by more complex product designs and upgraded specifications in the next generation of AI smartphones and foldable phones, further enhancing dollar content per device. In addition, with major brands accelerating the development of AI glasses, related revenue is expected to grow several-fold in 2026.
- 4 Actively expanding capacity to meet rising customer demand for high-end AI products:** We are actively expanding iHDI and HLC capacity at Huai'an and Thailand sites. iHDI and HLC capacity at the Huai'an campus is expected to double by the end of next year. In Thailand, fab 1 is steadily ramping up, with full utilization targeted for 2Q26. Construction of fab 2, 3, and 5, along with a mechanical drilling center, is progressing in parallel to meet growing demand for high-end AI products. At the Kaohsiung AI Park, installation and equipment testing of high-end ABF substrate and iHDI+HLC is underway, with the sampling phase scheduled to begin in 1Q26.

Business Overview

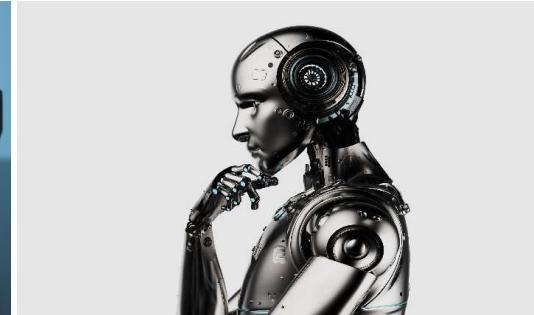
Edge AI-Related Applications



AI Smartphone/
Foldable Phone



Smart Glasses/VR/AR



Humanoid Robot

- We are the world's largest PCB manufacturer for AI glasses. Revenue from AI glasses grew severalfold in 2025, and with customer demand continuing to rise, it is expected to multiply again in 2026.
- New AI smartphones and foldable phones next year will feature more complex designs and upgraded specifications, further increasing the dollar content per device and contributing positively to overall performance.
- Humanoid robots have high technical requirements for PCBs, primarily used in core functions such as the main control system, sensor modules, power management, and joint actuators. We have established partnerships with multiple Mainland China and international customers, advancing product development and prototyping to meet high-end PCB requirements with high-precision and high-density interconnect solutions.

Server/Optical

- Leveraging our Huai'an and Thailand mass production campuses, we provide customers with Intelligent HDI (iHDI) and HLC products for AI server applications, focusing on next-generation platform development.
- At the Kaohsiung AI Park, we are conducting early-stage R&D for ultra high-end products, collaborating with customers on solutions for the next two to three platform generations.
- AI server revenue is expected to gradually scale up in 2026 and double in 2027.

IC Substrates

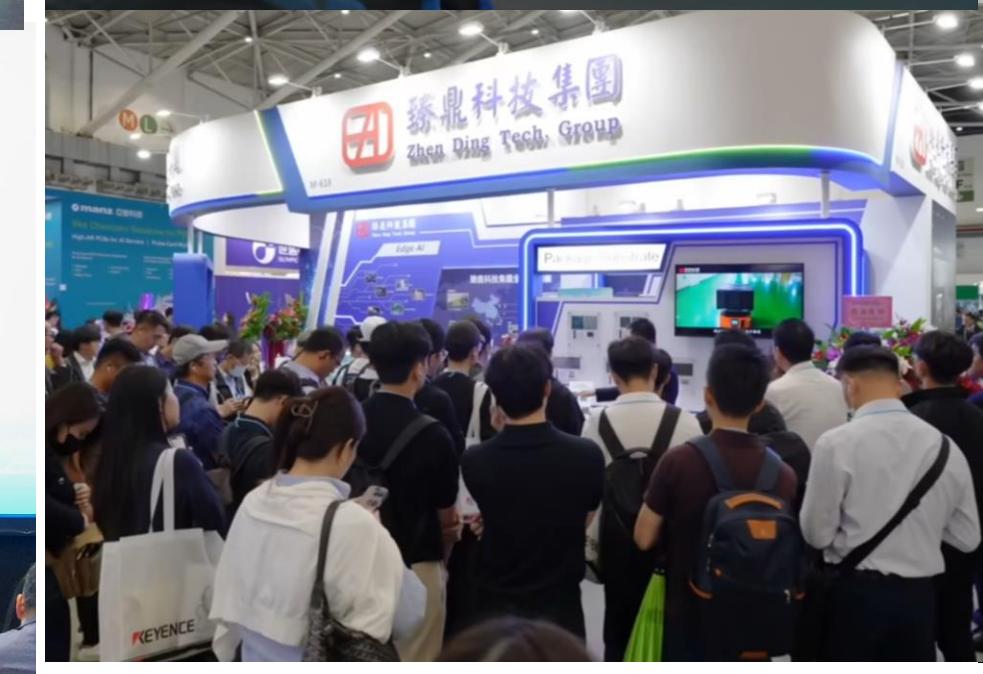
- Demand for BT substrates has shown a clear increase in 2H25, with average capacity utilization reaching around 90-95%. Capacity expansion at the Qinhuangdao plant is scheduled to begin in 1H26.
- Revenue contribution from large body size ABF substrates has continued to increase, with approximately 75% of ABF substrate revenue in September already coming from AI compute-related products. In addition, the number of sampling builds has risen sharply. We expect revenue contribution from ABF substrates to increase materially quarter by quarter throughout 2026.
- At the Kaohsiung AI Park, installation and equipment testing of high-end ABF substrate is underway, with the sampling phase scheduled to begin in 1Q26, supporting the needs of global customers.

By Participating in SEMICON Taiwan and TPCA, ZDT Showcases its Technological Leadership amid the Ongoing PCB Semiconductorization Trend

ZDT Once Again Participated in SEMICON Taiwan 2025



ZDT Participates in TPCA Show 2025 for the First Time

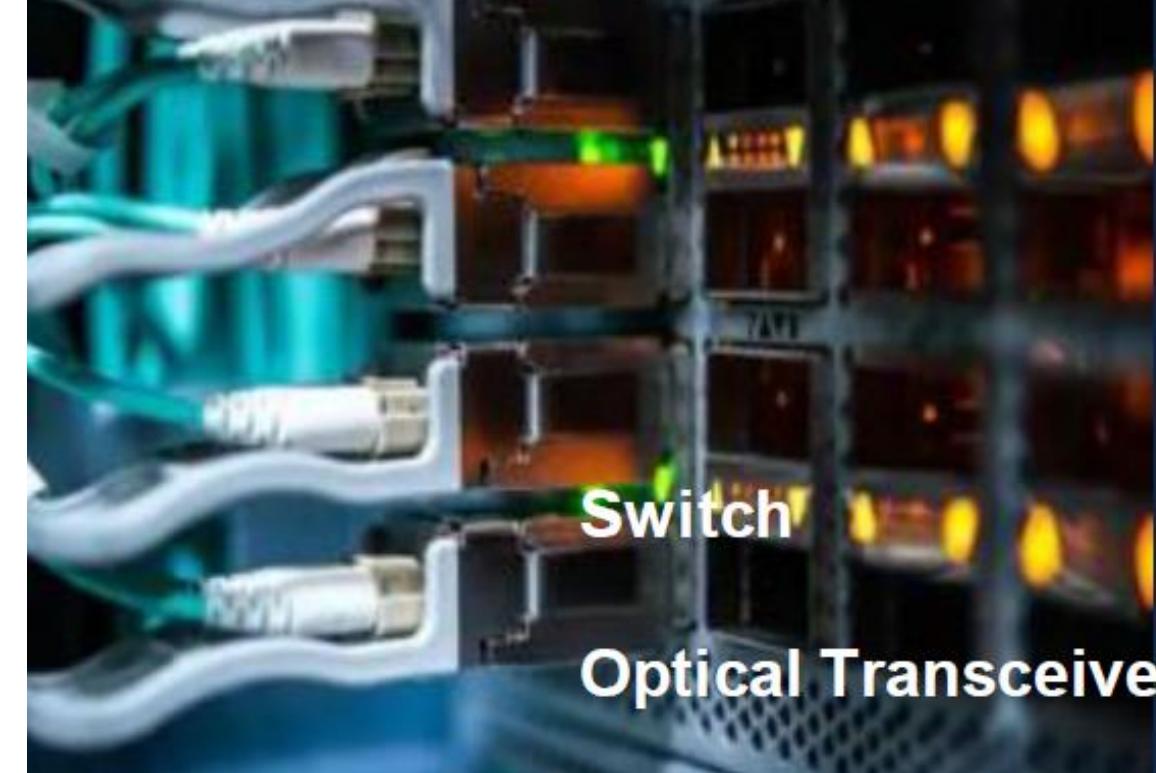


From Advanced PCB to IC Substrates, ZDT Provides Comprehensive Heterogeneous Integration Solutions

Cloud



Channel



Device



HLC

Intelligent HDI

ICS

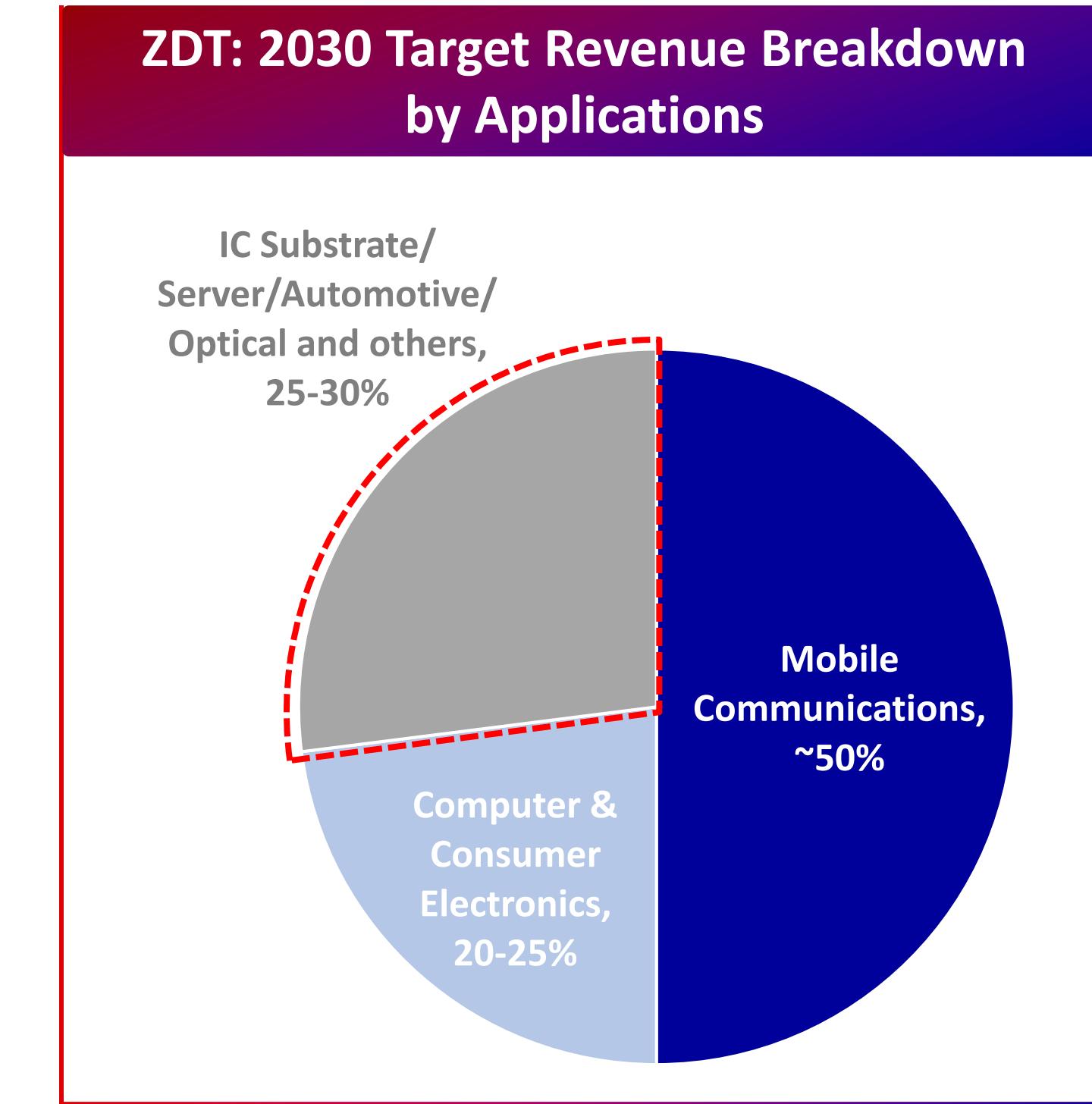
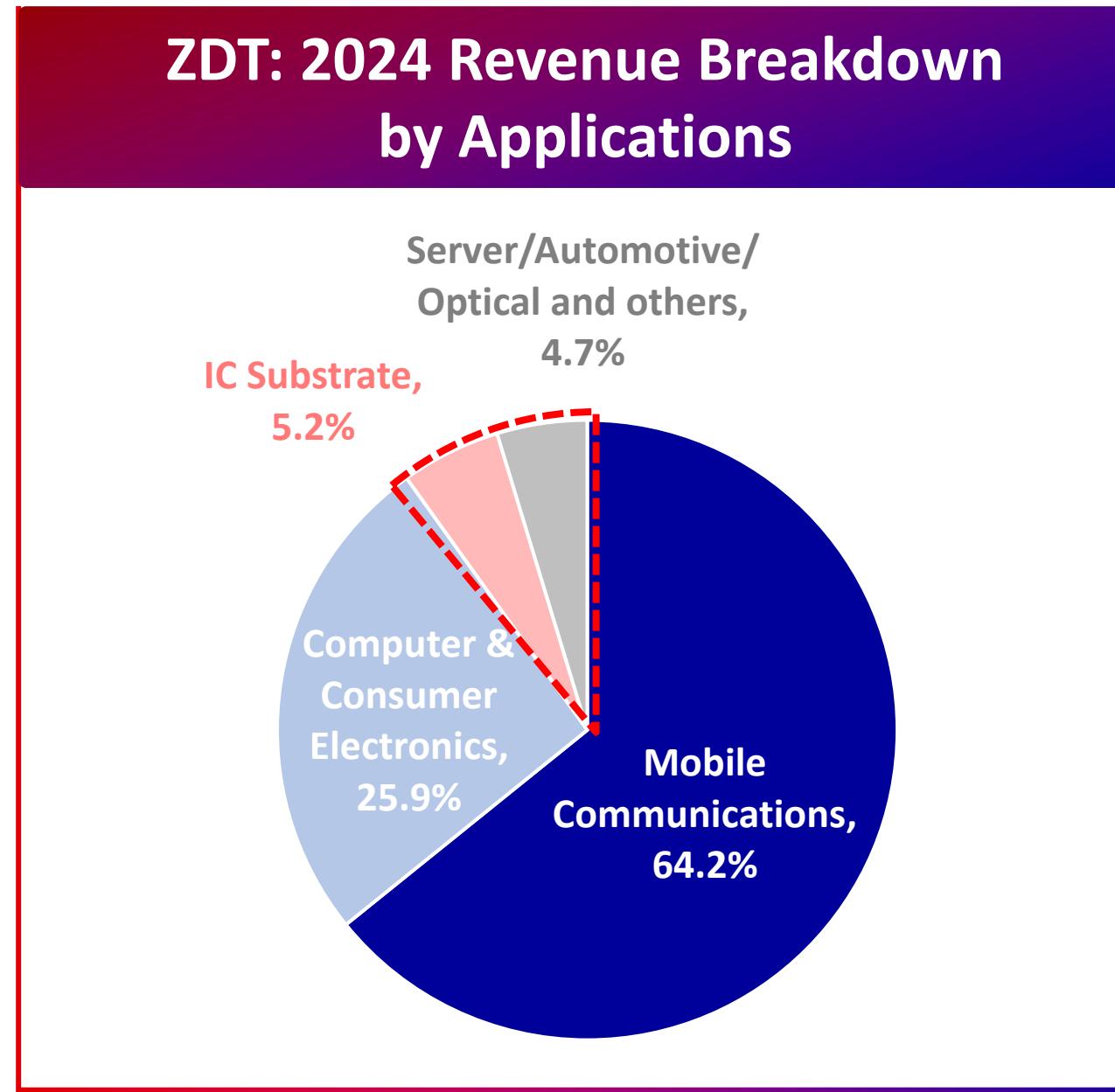
High Accuracy
HDI

High Density

Big Size & High
Stacked Layers

High Speed
Material

Steadily Advancing Server and IC Substrate Businesses to Drive Increasing Revenue Contribution





臻鼎科技控股
Zhen Ding Tech. Holding

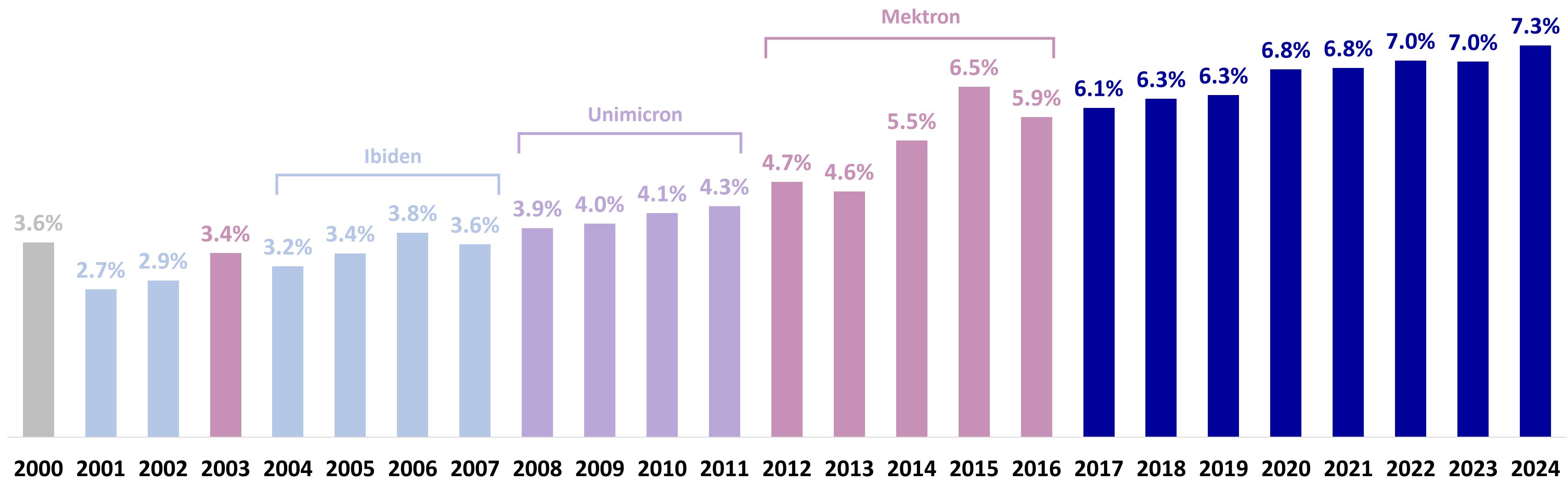
Strengthen Leadership Position
and Further Expand Market Presence

ZDT Sustains Its Leadership in the PCB Industry

Historical Market Share of Global #1 PCB Players

■ Sanmina ■ Ibiden ■ Mektron ■ UMTC ■ ZDT

ZDT has ranked #1 globally in the
PCB industry for **8 consecutive years**
(The first PCB company that surpassed a 7%
global market share)



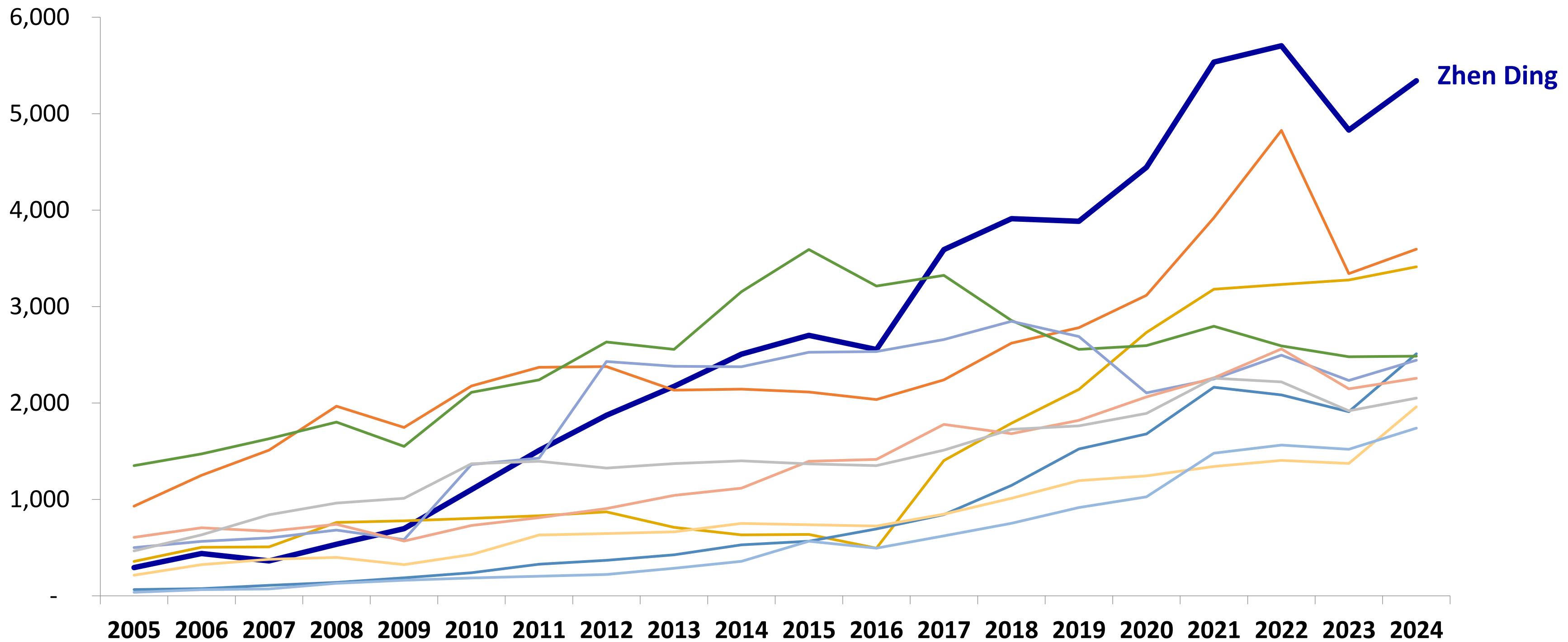
Source: Prismark

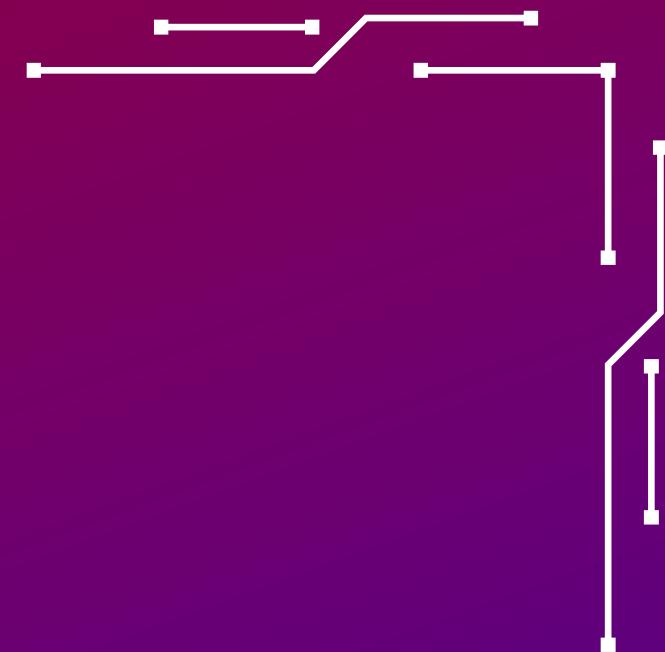
ZDT Maintains a Clear Lead Over Peers



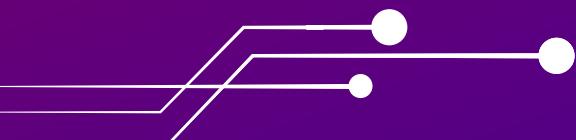
2024 Global Top 10 PCB Companies Revenue Trend

Unit: US\$ million



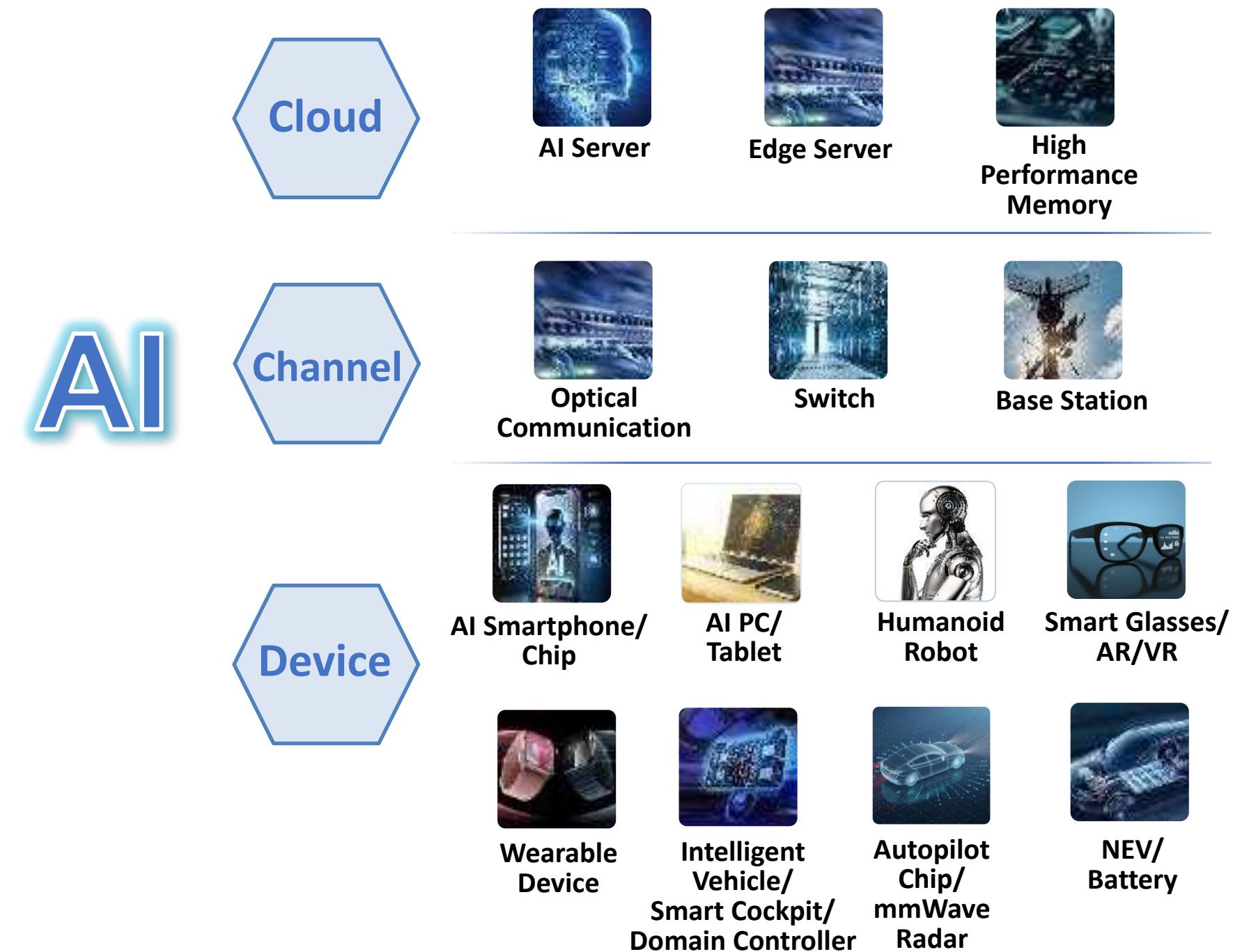
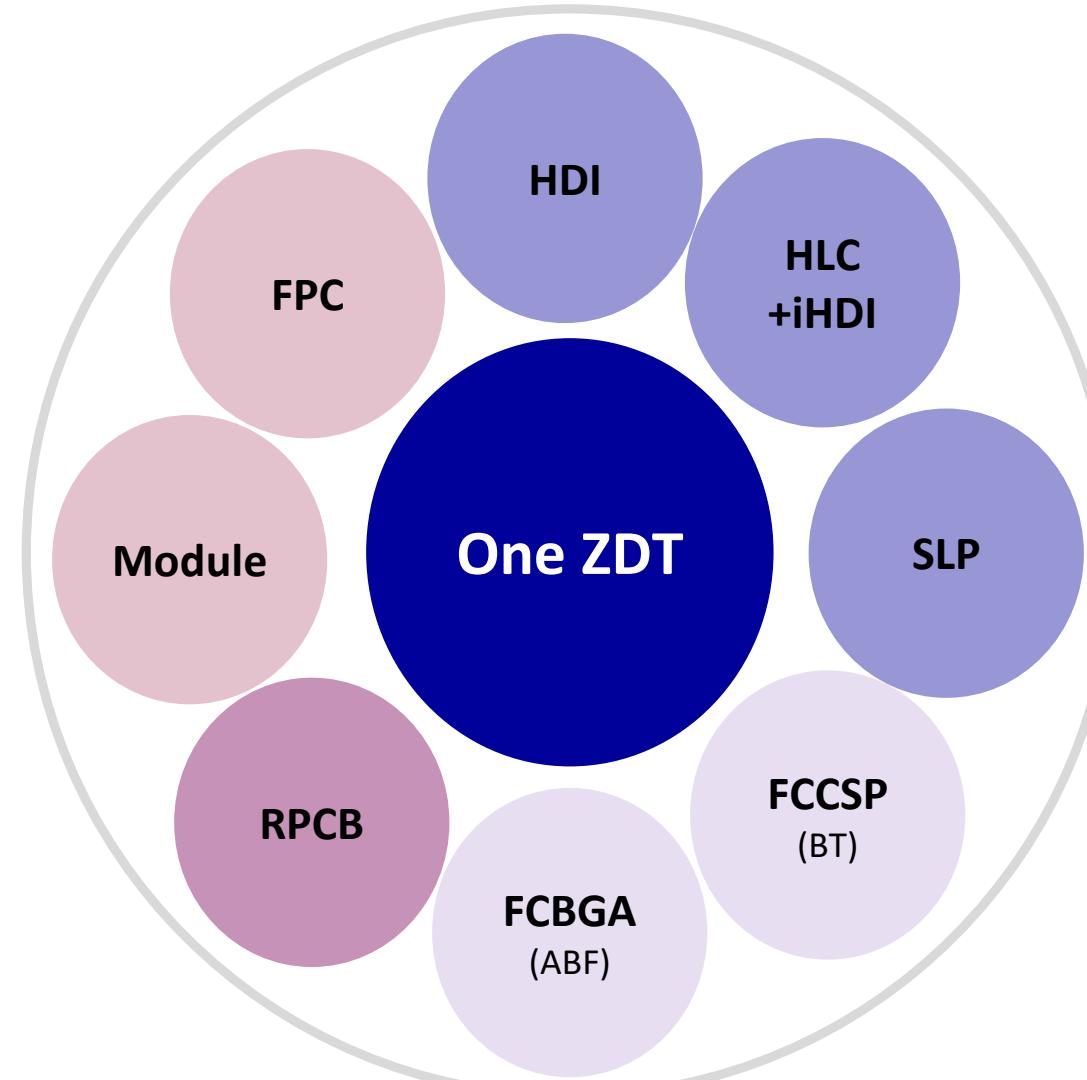


What enables ZDT to maintain our leadership position?



Zhen Ding: The Only PCB Leader with a Full-Range Product Portfolio

Leveraging our full product portfolio under the 'One ZDT' strategy, we deliver end-to-end solutions across cloud, channel, and edge applications in the AI era — reinforcing our leadership in an increasingly complex PCB landscape.



AI as a Key Growth Driver for the PCB Industry; Zhen Ding Leveraging Full-Product Advantage to Extend Its Lead in the AI Era

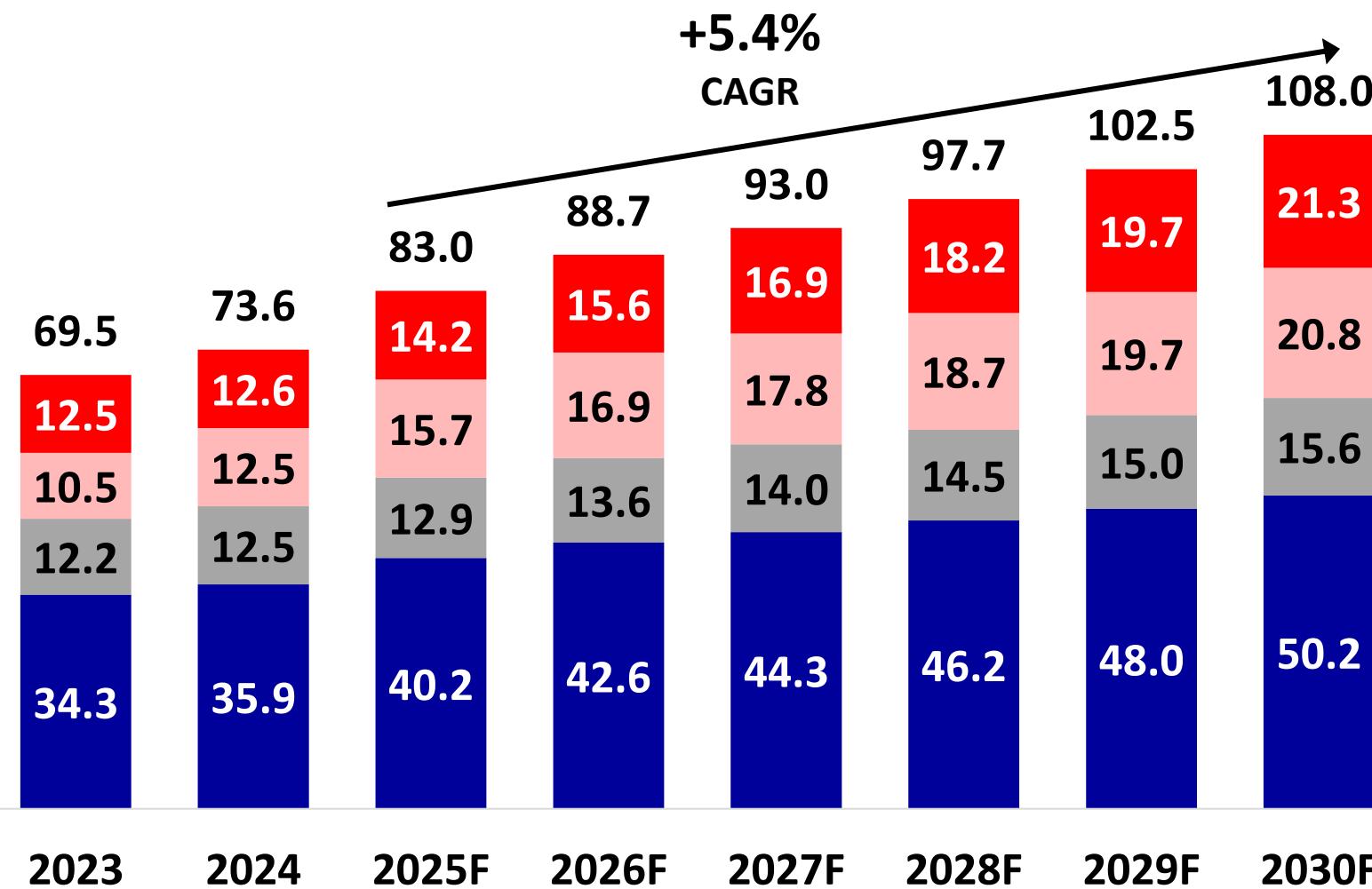
All PCB Categories Benefit from AI-Driven High-Performance Requirements and Product Innovation; AI to Remain the Core Growth Driver for the PCB Industry in the Coming Years

Zhen Ding Delivers End-to-End Solutions across Cloud, Channel & Edge Applications in the AI Era, with a Growing AI Revenue Contribution

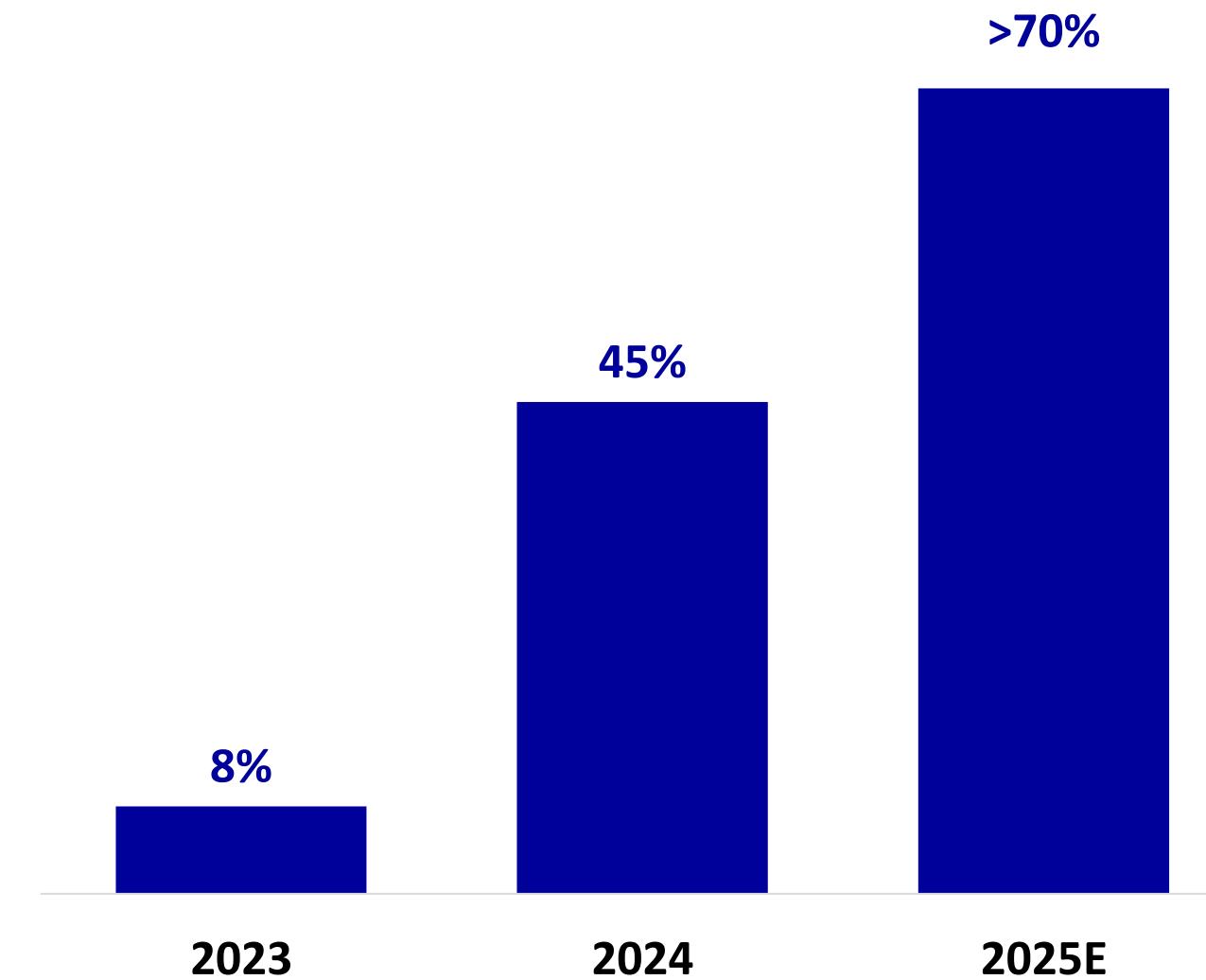
Global PCB market size by product category

(Unit : US\$bn)

■ RPCB ■ FPC ■ HDI ■ ICS



■ ZDT: Revenue Contribution for AI Related Products

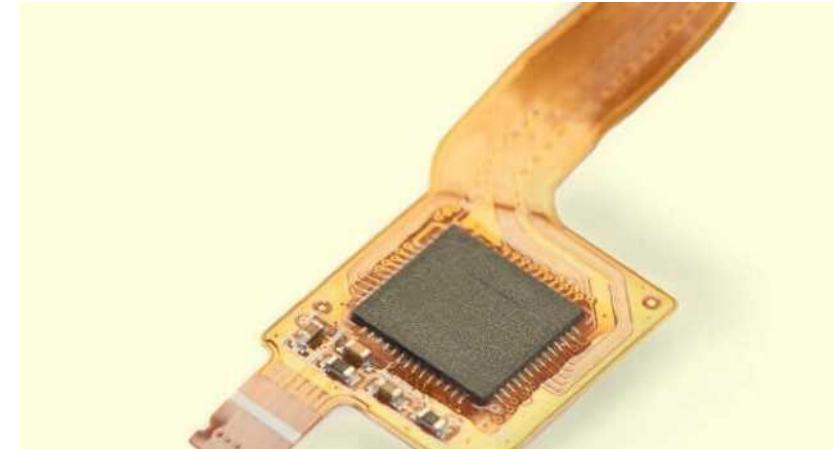


Source: Prismark (2025/9); 2026~30's data is calculated based on Prismark's estimation.

Years of Development Bearing Fruit; Zhen Ding's Four Product Lines Poised for Continued Growth



IC Substrate



Flexible Printed Circuit (FPC)



High Density Interconnect (HDI)



Rigid PCB (RPCB)

2030 Target

Global Top 5

2030 Target

Maintain
Global #1

2030 Target

Global #1

2030 Target

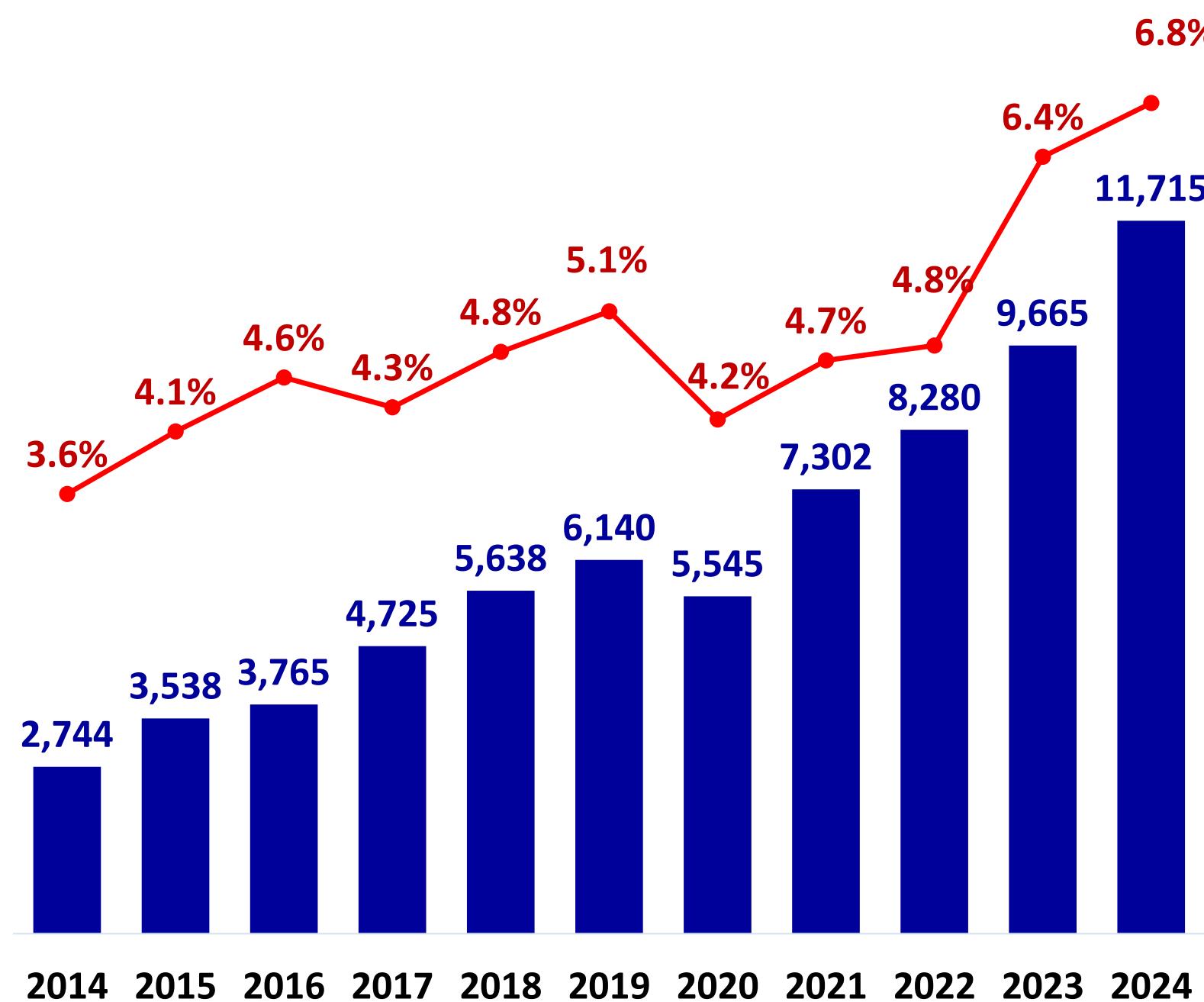
Global Top 10

Deepening collaboration with customers and supply chain partners
to deliver above-industry-average revenue and profit growth

Ongoing R&D Investment in Advanced Products to Sustain Market Leadership

■ R&D Expense ● R&D Expense / Revenue

Unit: NT\$ million



ZDT follows 12 R&D principles in our PCB and semiconductor development initiatives, focusing on the R&D of advanced technologies and their application in next-generation products.

12 R&D Principles:



We have established R&D centers in both Taiwan and Mainland China. We continue to enhance our new technology development capabilities to maintain leadership in high-end products and technologies.



Disciplined Capacity Expansion,
Advancing Steadily to Seize Market Opportunities

Global Production Footprint Continues to Expand, with Benefits Expected to Materialize Starting Next Two Years



Mainland China



Thailand Prachinburi Park



Kaohsiung AI Park

Capacity Expansion Plan

- From 2H25 to 2028, we plan to invest RMB 8 billion to expand high-end PCB capacity at the Huai'an campus.
- By the end of 2026, iHDI and HLC capacity at the Huai'an site is expected to double compared with the current level.

- Fab 1 began trial production on May 8 and is ramping up smoothly, with full utilization targeted for 2Q26.
- Construction of fab 2, 3, and 5, along with a mechanical drilling center, is progressing in parallel to meet customers' growing demand for high-end AI products.

- Invest NT\$8bn in equipment to establish a full-process FCBGA mass production facility for the most advanced packaging.
- Invest NT\$2bn in equipment to build iHDI+HLC PCB production capacity.
- FPC production lines have begun mass production and are contributing to revenue.

Strategy to Enhance Operational Efficiency

- Each fab will implement smart manufacturing and digital transformation in phases to improve operational efficiency, increase per capita productivity, and further enhance overall profitability and competitiveness.

- We have passed qualifications from multiple customers, and several leading global server and optical customers are in active qualification; Thailand fab 1 focuses on high-end iHDI, HLC and optical module products, with mass production to enhance product mix and margins.

- Plan to manufacture ultra-high-end products (30L–80L).
- Installation and equipment testing of high-end ABF substrate and iHDI+HLC is underway, with the sampling phase scheduled to begin in 1Q26.

Establish Diverse Production Bases with Advanced Capacities To Meet Global Customer Demands

India



Chennai Park

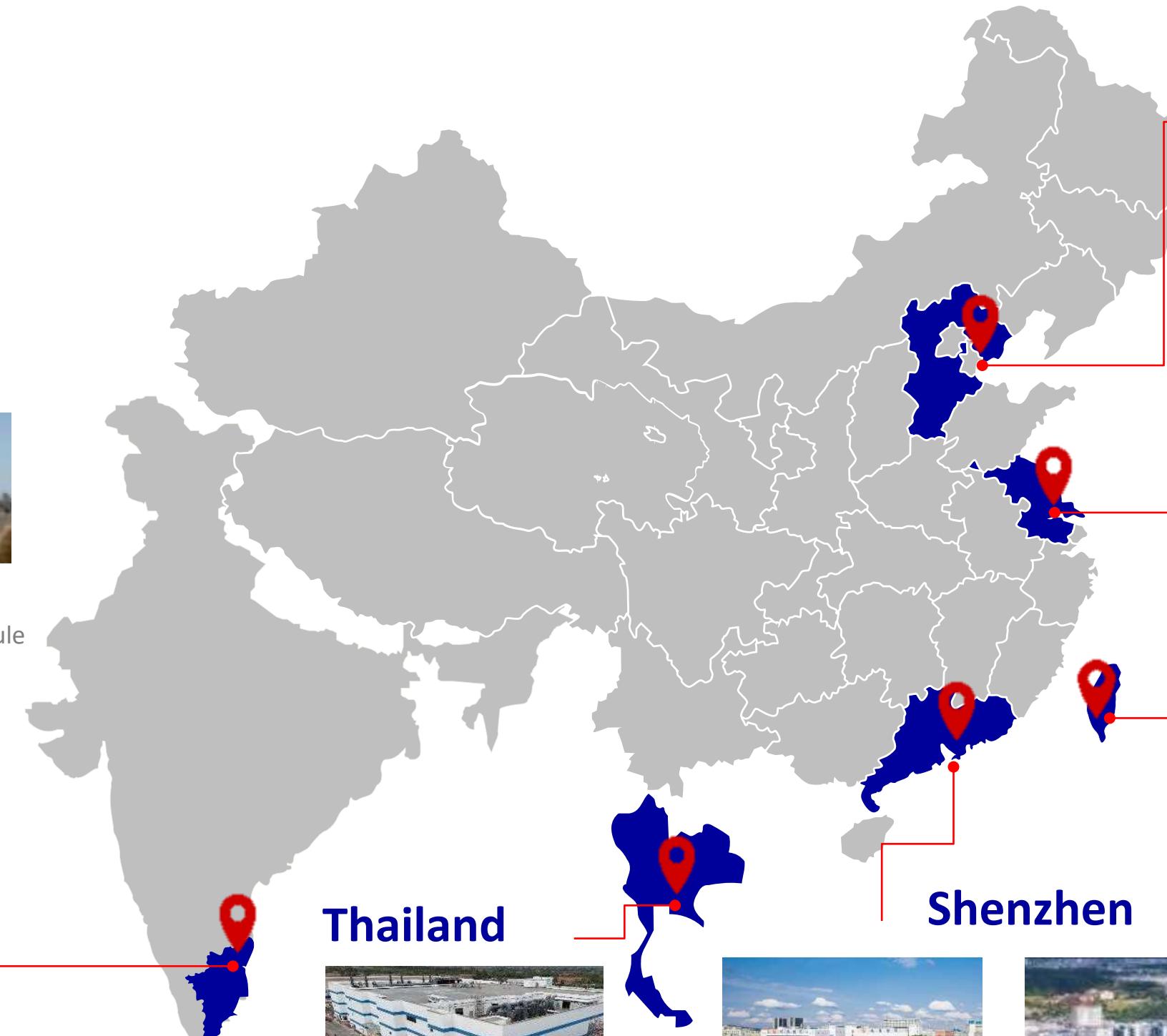
FPC and advanced module

Thailand



Prachinburi Park

Entered trial production
on May 8, 2025



Shenzhen



Shenzhen Park 1

FPC and advanced
module/HDI



Shenzhen Park 2

FPC and advanced
module

Qinhuangdao



Qinhuangdao Park

FPC & advanced
module/SLP High end HDI



BT Substrate Park

FC-CSP/WB-
CSP/Memory, phase 1
entered mass
production in 2022

Huai'an



Huai'an Park 1

RPCB/HDI



Huai'an Park 2

FPC & advanced
module/HDI/ Mini LED



Huai'an Park 3

High-end HDI/MSAP,
entered mass
production in 2023

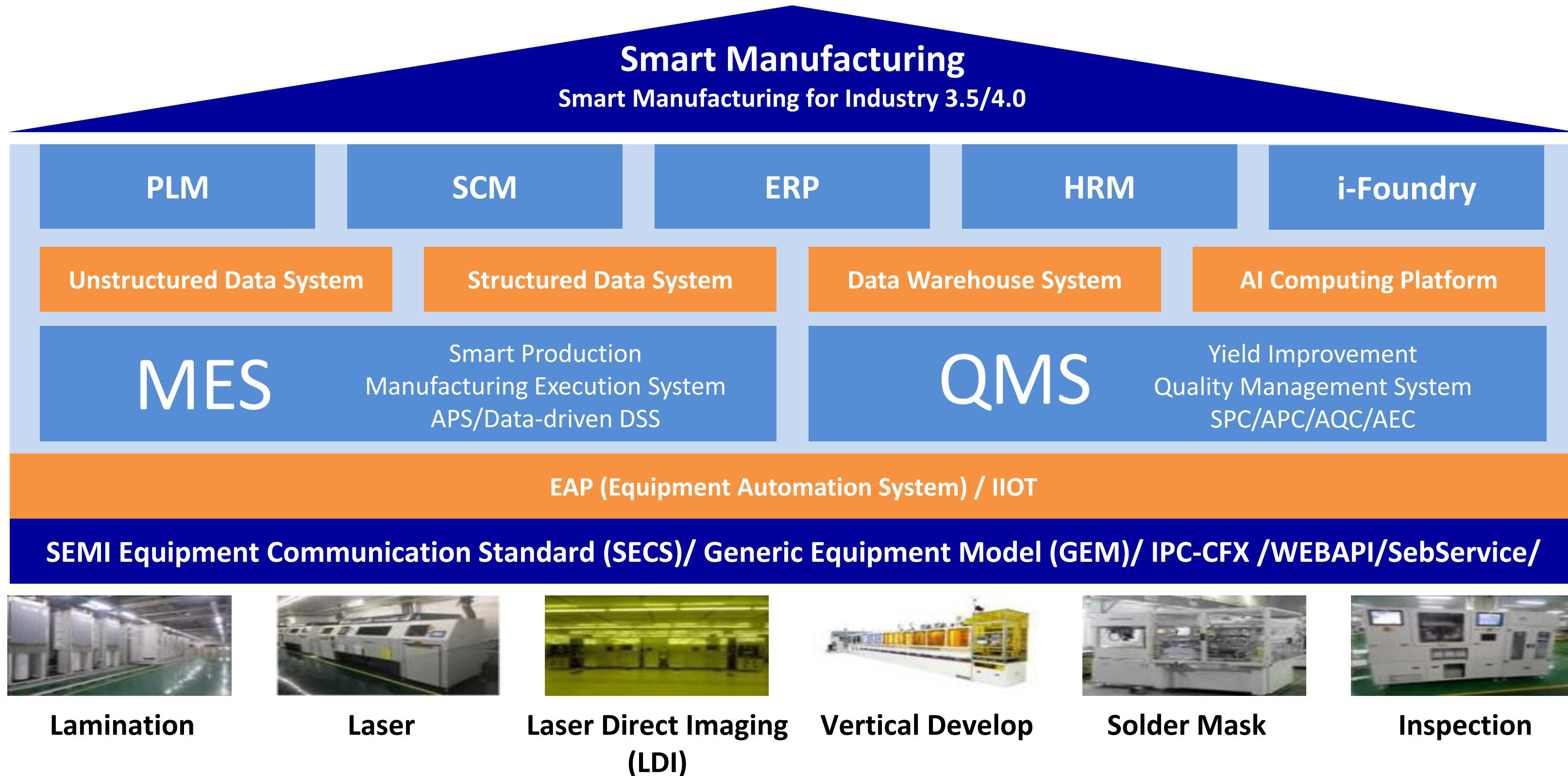
Taiwan



Kaohsiung AI Park

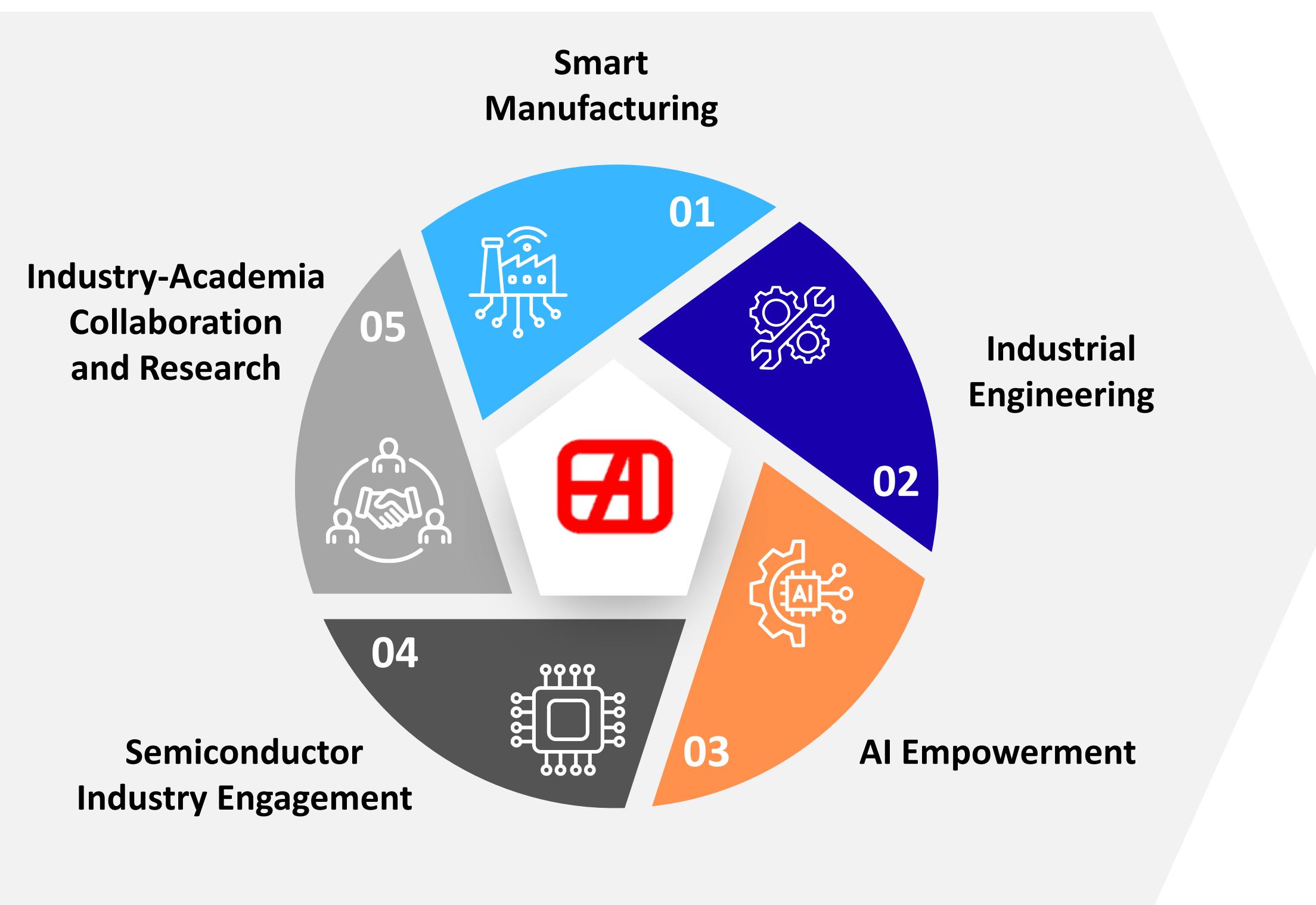
R&D and Manufacturing
Site for AI Products

Leverage Smart Manufacturing to Increase Per Capita Productivity and Enhance Profitability



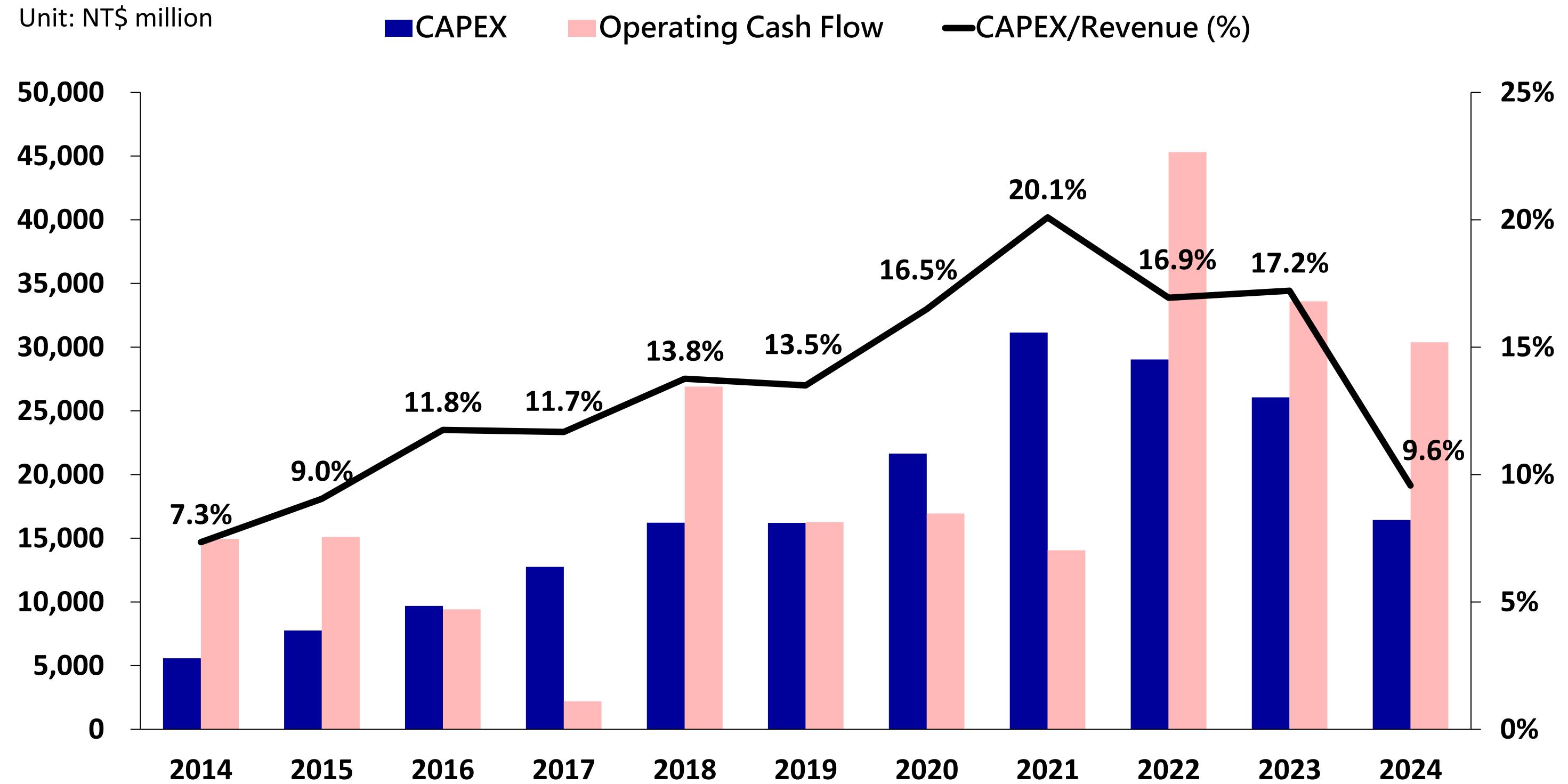
Operational Digitization, Platform Digitalization, Platform Intelligence, and Intelligent Implementation

Empowering the Team to Strengthen Zhen Ding's Operational Resilience and Sustainable Competitiveness

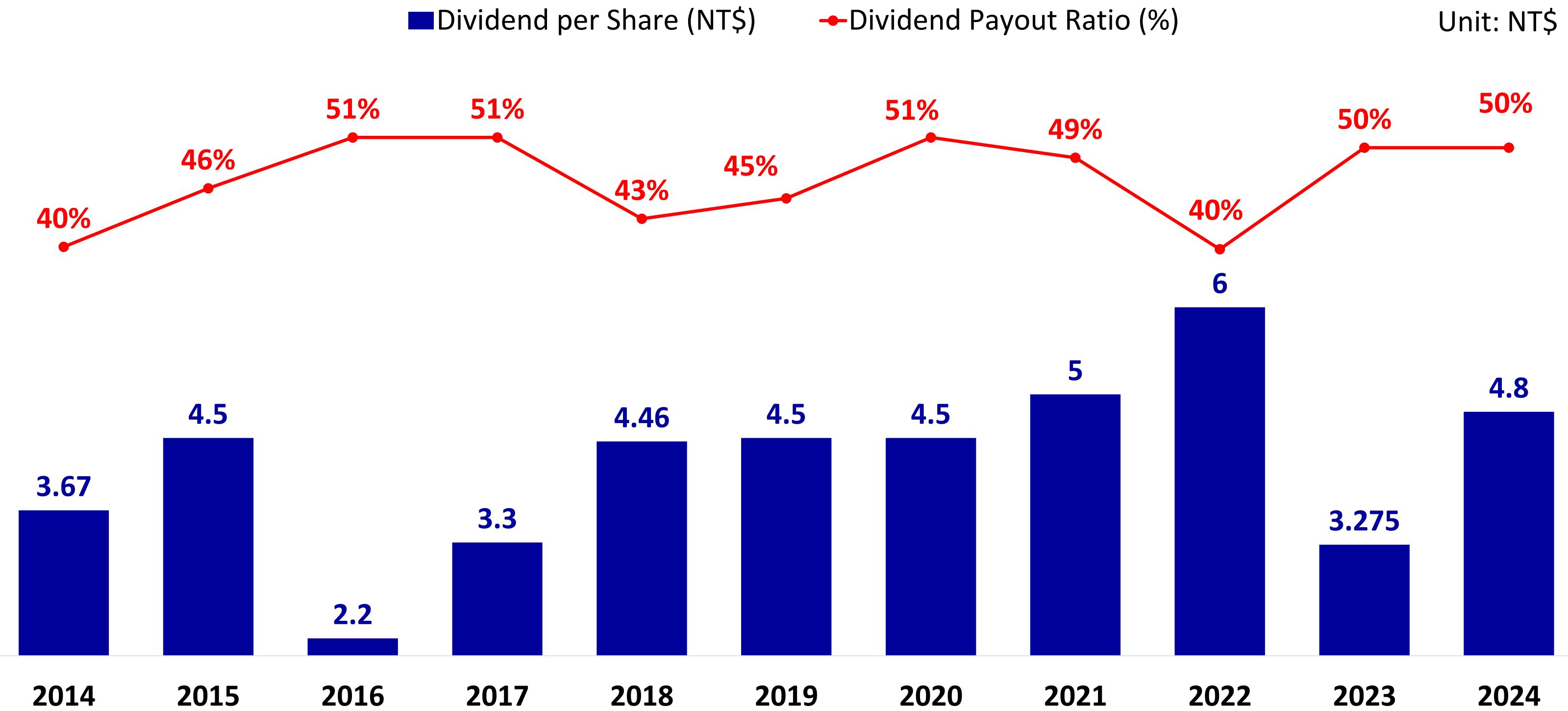


Enhance internal and external resource integration to achieve team empowerment and structural optimization.

With Strong Cash Flow, We Prudently Manage CAPEX, Ensuring Stability in the Face of Macroeconomic Changes



Maintain High Dividend Payout Ratios; Share Business Success With Shareholders



EPS + ESG – Improvement of ESG Ratings

► Corporate Governance Evaluation Ranking

Ranked between 6% to 20% in the 2025 Corporate Governance Evaluation for listed companies and **re-selected for inclusion in the TWSE Corporate Governance 100 Index.**

► S&P Global ESG Rating

In 2025, our S&P ESG Score improved to 85. From 2022 to 2024, we were **selected as the only PCB company in the S&P Global Sustainability Yearbook** for the third consecutive year.

► Sustainalytics ESG Risk Rating

Our latest Sustainalytics ESG Risk Ratings was 16.1, classified as **low risk.**



► ISS ESG Rating

ISS has upgraded our ESG Rating from "C" to "C+," granting Zhen Ding **"Prime" status.**

► CDP

In 2024, we received an **'A' leadership** rating for water security, marking a one-notch improvement from last year. Additionally, we achieved a 'B' rating from CDP for climate change.

► FTSE Russell ESG Rating

Our latest FTSE Russell ESG Rating reached 4.5 (out of 5) and **ranked first among PCB companies in Taiwan.**



Advanced Technologies to Fuel Rapid Growth in IC Substrates

Embracing 'China for China' Demand, While Expanding the Outside China Customer Base with Advanced Packaging ABF Substrates



In 2023, over 130 ABF substrate samples were delivered, and progressively passed customer qualifications.

2024 IC substrate revenue increased by 75.6% YoY, significantly outperforming the industry average growth

Target to Rank among the Top Five Global IC Substrate Manufacturers by 2030

Focus on High-end Demand

- With the industry's most advanced IC substrate production base, we focus on meeting the high-end demands of customers.
- The rapid development of AI, HPC, and advanced packaging technologies continues to drive demand for high-end ABF substrates, particularly for large-size (70mm × 70mm and above) and high-layer-count (16 layers and above) products.



Connect with the Semiconductor Supply Chain

- Actively engage with semiconductor industry organizations and collaborate closely with the supply chain to explore market opportunities in emerging technologies.



Replicate China Experience at Kaohsiung AI Park

- Our Mainland China ABF fab is highly recognized by customers for its high quality, yield, and efficiency, with capacity utilization steadily increasing.
- We will replicate the successful experience from Mainland China and establish a full-process advanced packaging FCBGA mass production site at the Kaohsiung AI Park, focusing on developing key semiconductor customers in Asia, the U.S, and Europe.
- We are the first PCB manufacturer to establish a presence in Taiwan's Science Park, meeting high standards in both technology and environmental protection.

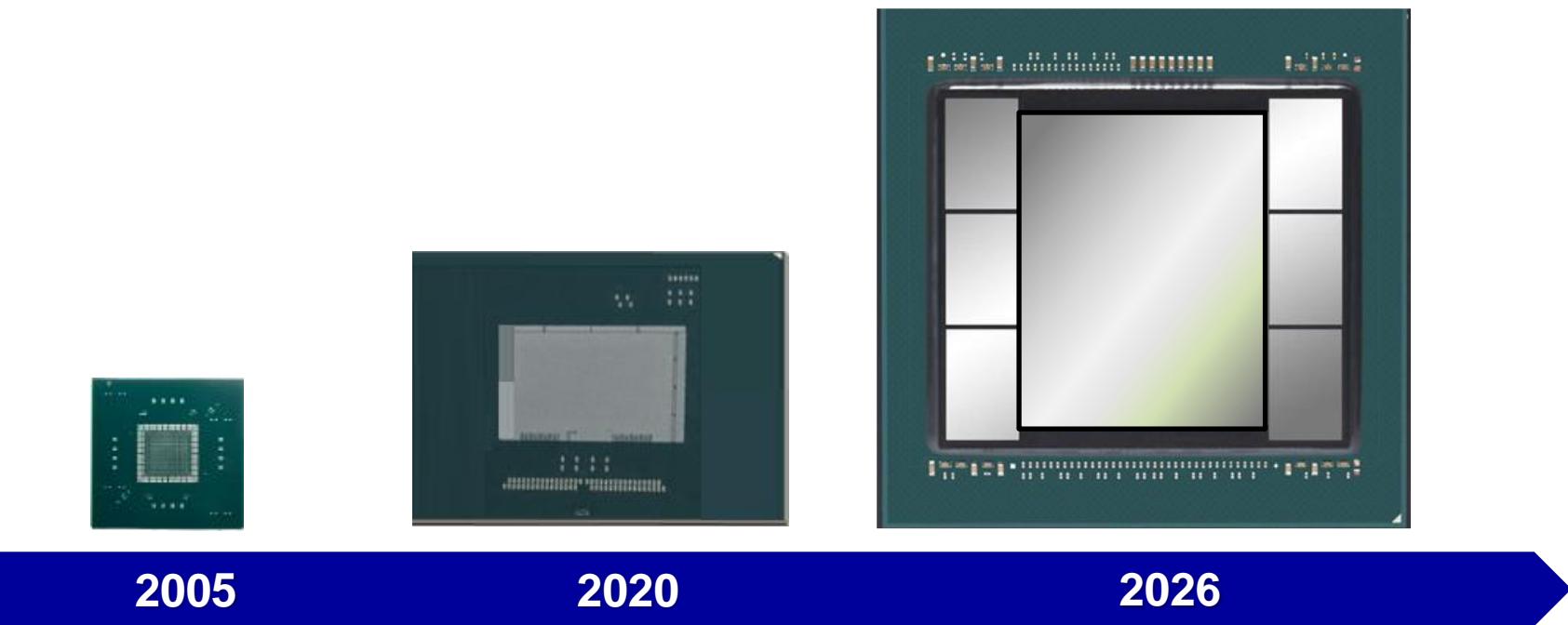


ZDT's ABF Substrate Technology Capabilities are On Par with Tier 1 Players; We Actively Secure Global Leading Semiconductor Customers

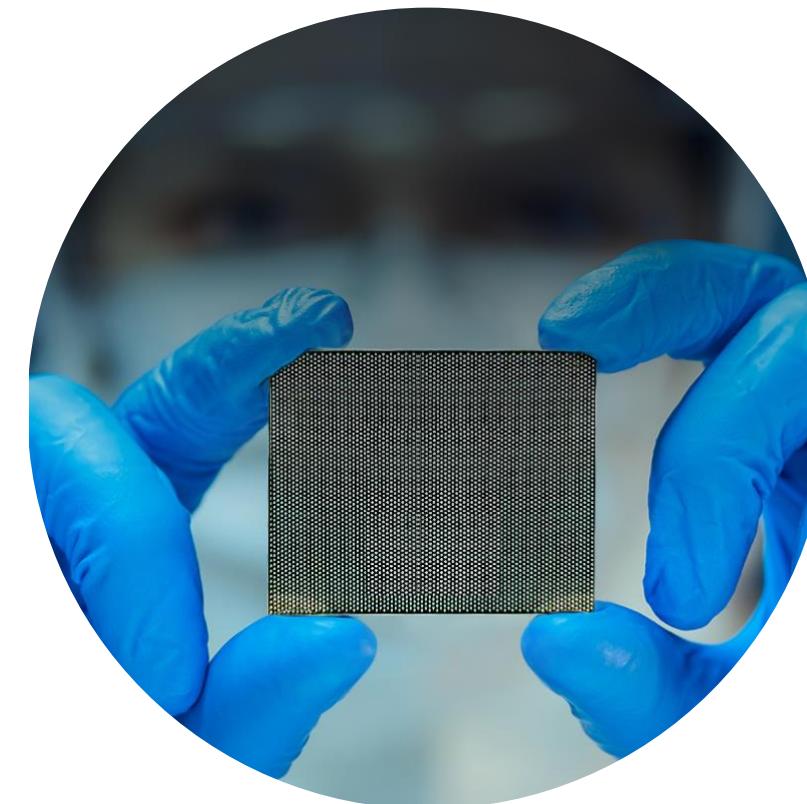
ABF Substrate Development Trends

High layer counts, **Large** body size, **Flat** surface,
Accurate production precision

Our technology capabilities have reached an industry-leading level



	2005	2020	2026	
Body Size (mm)	31 x 31	75 x 60	120 x 140+	x20+
Layer count (L)	6	20	28+	x4+
Bump Count	1K	100K	300k+ ~ 500k+	x300+





臻鼎科技控股
Zhen Ding Tech. Holding

Financial Summary

3Q25 Financial Results

Unit: NT\$ million, unless otherwise stated

	3Q25	3Q24	YoY (%)
Revenue	47,366	50,609	-6.4%
Gross Profit	10,410	11,406	-8.7%
Gross Margin	22.0%	22.5%	-0.5ppts
Operating Expense	5,880	5,473	+7.5%
Operating Profit	4,530	5,933	-23.6%
Operating Margin	9.6%	11.7%	-2.1ppts
Non-Operating Income/Expense	131	(655)	
Net Income	3,589	4,751	-24.5%
Net Margin	7.6%	9.4%	-1.8ppts
Net Income to Parent	2,392	3,353	-28.7%
EPS (NT\$)⁽¹⁾	2.46	3.52	
Depreciation and Amortization	4,522	4,517	+0.1%
Cash Inflow Generated from Operations	(2,847)	(712)	
Cash and Cash Equivalents ⁽²⁾	76,608	64,714	+18.4%
ROE(%) ⁽³⁾	9.4%	13.7%	-4.3ppts

Note : (1) Weighted Average Shares outstanding as of 9M25 : 973,212 thousand shares (actual issuance 1,040,623 thousand shares, with 424 thousand shares held in treasury)
(2) Including current financial assets at amortized cost (time deposits, etc.) (3) ROE is annualized data calculated based on the average of equity attributable to owners of parent

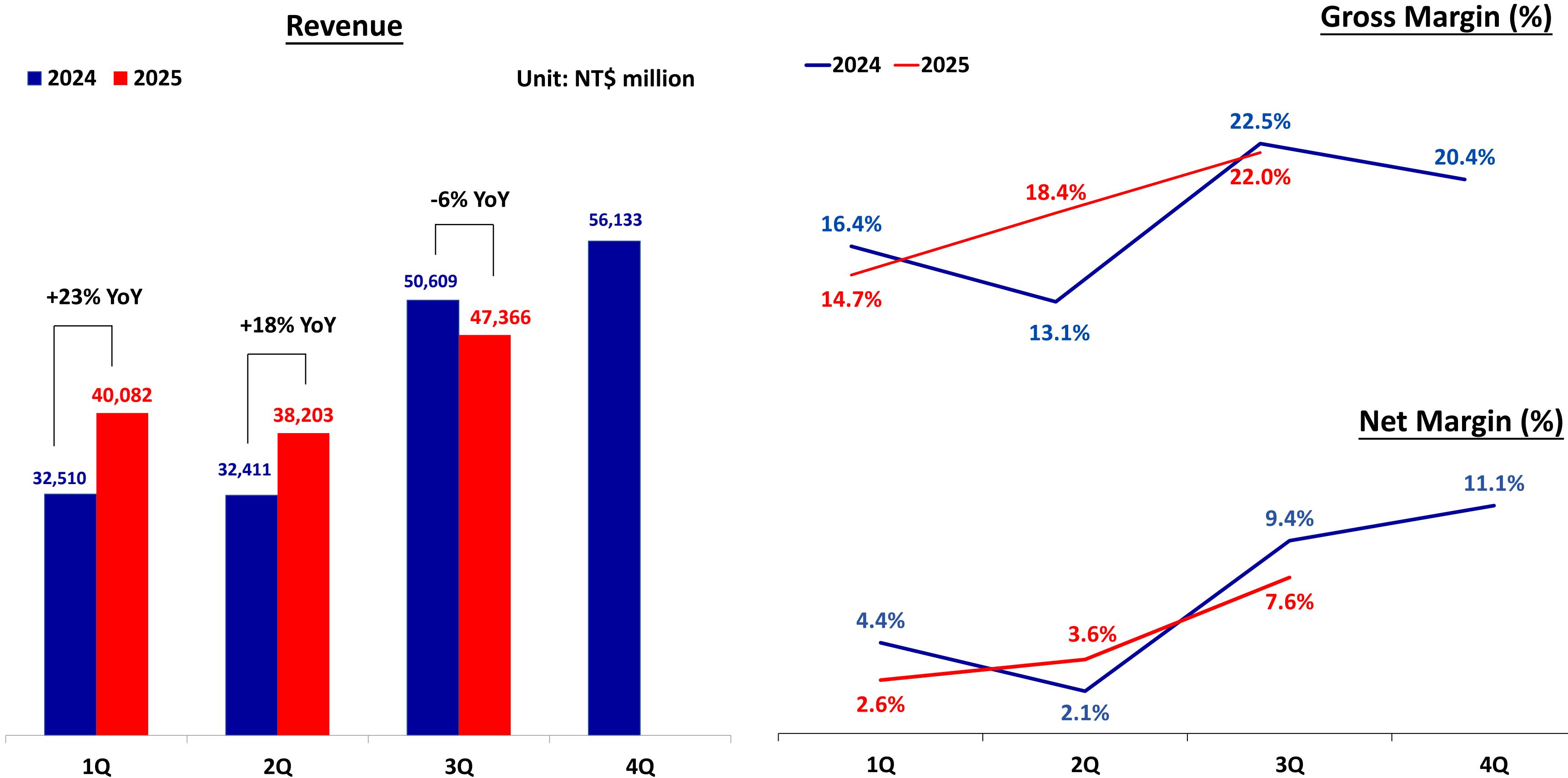
1-3Q25 Financial Results

Unit: NT\$ million, unless otherwise stated

	1-3Q25	1-3Q24	YoY (%)
Revenue	125,652	115,531	+8.8%
Gross Profit	23,306	20,990	+11.0%
Gross Margin	18.5%	18.2%	+0.3ppts
Operating Expense	15,296	14,958	+2.3%
Operating Profit	8,011	6,032	+32.8%
Operating Margin	6.4%	5.2%	+1.2ppts
Non-Operating Income/Expense	379	1,253	-69.7%
Net Income	6,002	6,855	-12.4%
Net Margin	4.8%	5.9%	-1.1ppts
Net Income to Parent	3,629	4,816	-24.6%
EPS (NT\$)⁽¹⁾	3.79	5.08	
Depreciation and Amortization	13,777	13,094	+5.2%
Cash Inflow Generated from Operations	15,407	9,404	+63.8%
Cash and Cash Equivalents ⁽²⁾	76,608	64,714	+18.4%
ROE(%) ⁽³⁾	5.2%	6.6%	-1.4ppts

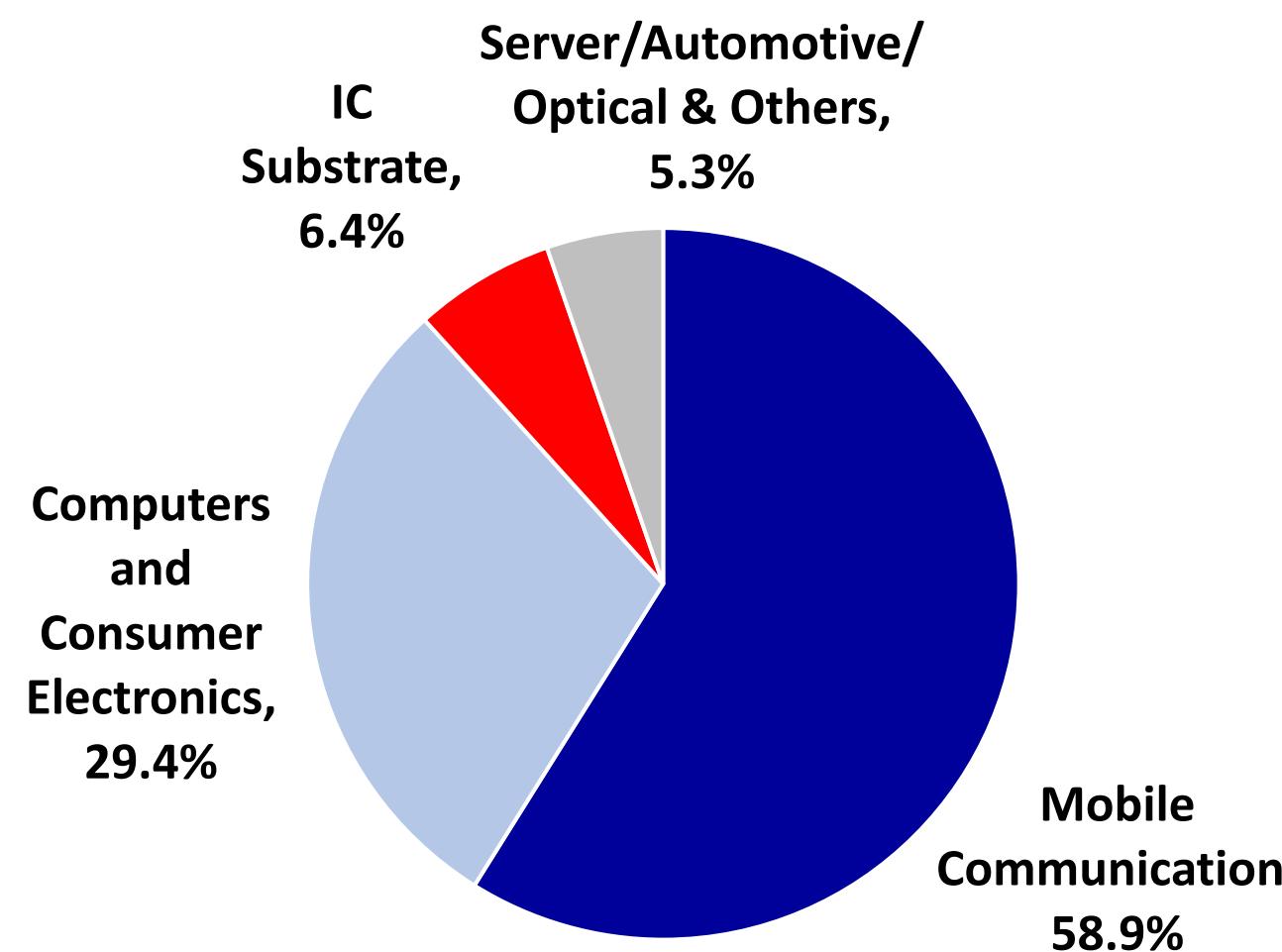
Note : (1) Weighted Average Shares outstanding as of 9M25 : 957,280 thousand shares (actual issuance 1,040,623 thousand shares, with 424 thousand shares held in treasury)
 (2) Including current financial assets at amortized cost (time deposits, etc.) (3) ROE is annualized data calculated based on the average of equity attributable to owners of parent

Quarterly Operation Results

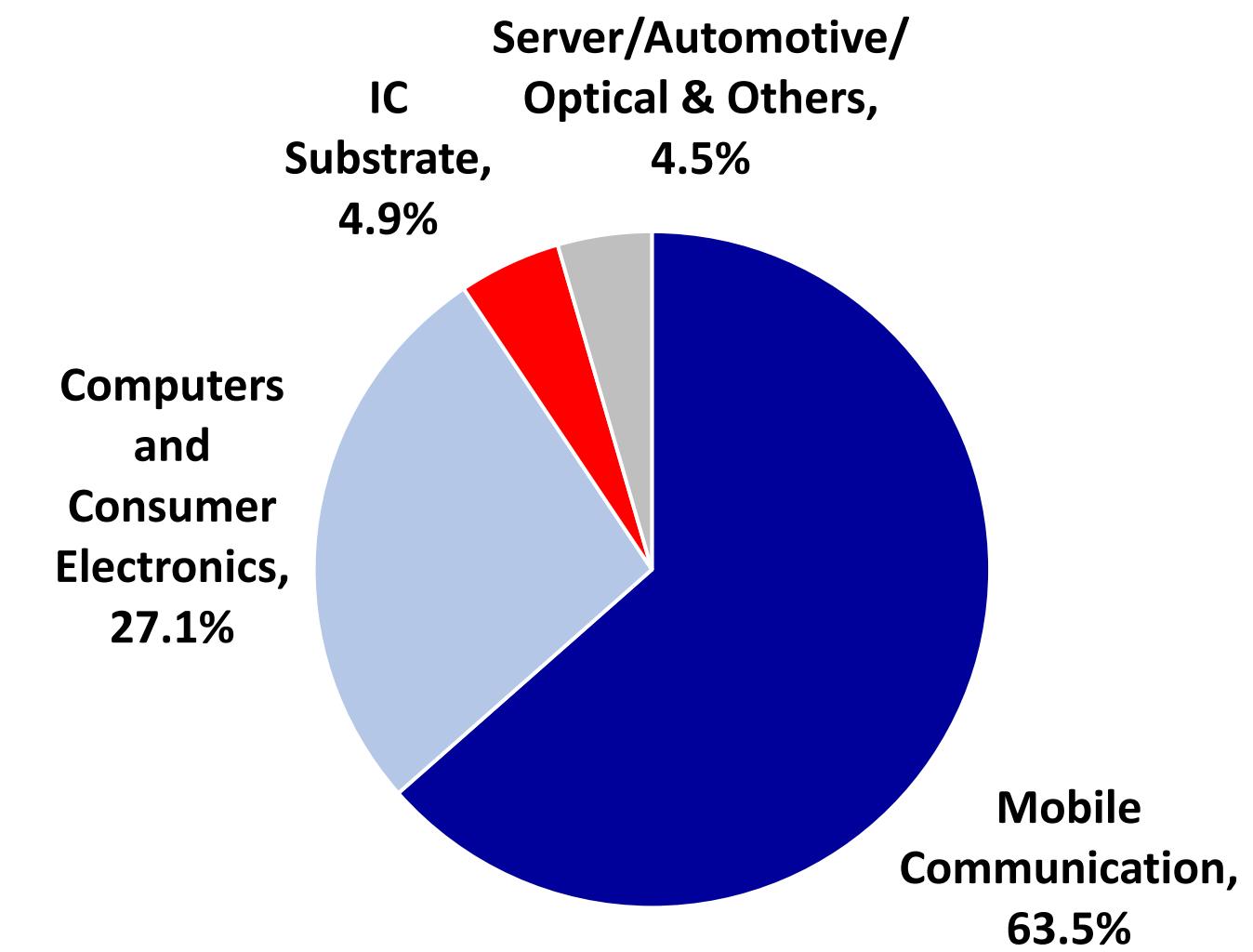


Revenue Breakdown – By Applications

3Q25 Revenue NT\$47.4bn



3Q24 Revenue NT\$50.6bn



Consolidated Balance Sheet and Key Indices

	Unit: NT\$ million					
	2025-9-30		2024-9-30		Change	
	Amount	%	Amount	%	Amount	%
Cash and Cash Equivalents ⁽²⁾	76,608	27.9%	64,714	24.9%	11,894	+3.0ppts
Notes & Accounts Receivable	30,609	11.1%	35,675	13.7%	(5,066)	-2.6ppts
Inventories	22,420	8.2%	24,799	9.5%	(2,379)	-1.3ppts
Property, Plant and Equipment ⁽³⁾	118,742	43.2%	111,026	42.8%	7,716	+0.4ppts
Total Assets	274,788	100.0%	259,685	100.0%	15,103	
Debt	63,999	23.3%	56,260	21.7%	7,739	+1.6ppts
Notes & Accounts Payable	43,510	15.8%	43,776	16.9%	(266)	-1.1ppts
Total Liabilities	120,979	44.0%	115,599	44.5%	5,380	-0.5ppts
Total Equity	153,809	56.0%	144,087	55.5%	9,722	+0.5ppts
Key Indices						
A/R Turnover Days	66		77		(11)	
Inventory Turnover Days	57		62		(5)	
Current Ratio (x)	1.59		1.78		(0.19)	
PPE Turnover (x) ⁽⁴⁾	1.44		1.39		0.05	

Note : (1) Weighted Average Shares outstanding as of 9M25 : 957,280 thousand shares (actual issuance 1,040,623 thousand shares, with 424 thousand shares held in treasury (2) Including current financial assets at amortized cost (time deposits, etc.) (3) PPE includes investment property (4) PPE Turnover = annualized net revenue / average net property, plant and equipment

2015-2024 Financial Summary

Unit: NT\$ million

Period	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024
Revenue	85,738	82,393	109,238	117,913	120,068	131,279	155,022	171,356	151,398	171,664
Gross Profit	16,427	12,542	17,833	26,061	27,222	26,584	30,537	39,888	27,459	32,461
Net Income	7,731	3,456	6,772	11,536	12,402	11,508	13,694	20,535	9,432	13,096
Net Income to Parent	7,731	3,456	5,172	8,448	8,685	8,095	9,651	14,197	6,189	9,180
Depreciation & Amortization	4,850	5,295	5,679	6,820	7,955	8,405	11,875	14,638	16,323	17,749
EPS (NT\$)	9.80	4.29	6.43	10.50	9.93	8.90	10.21	15.02	6.55	9.67
DPS (NT\$)	4.50	2.20	3.30	4.46	4.50	4.50	5.00	6.00	3.275	4.80
Payout Ratio (%)	46%	51%	51%	43%	45%	51%	49%	40%	50%	50%
Cash and Cash Equivalents*	31,572	30,241	33,296	49,154	43,071	46,775	35,179	57,599	65,970	79,830
Property, Plant and Equipment	32,074	32,262	36,681	41,913	46,243	68,177	86,073	104,814	109,965	113,462
Capital	8,047	8,047	8,047	8,047	9,022	9,470	9,470	9,470	9,470	9,567
ROE (%)	20.82%	8.59%	14.49%	17.30%	14.72%	11.84%	12.59%	16.67%	7.10%	9.15%
Debt Ratio (%)	53.70%	59.72%	55.33%	44.25%	35.41%	42.56%	42.01%	42.87%	44.67%	42.85%

* Including current financial assets at amortized cost (time deposits, etc.)



Thank You